

Tpcm 7000 Solder Reflow Test



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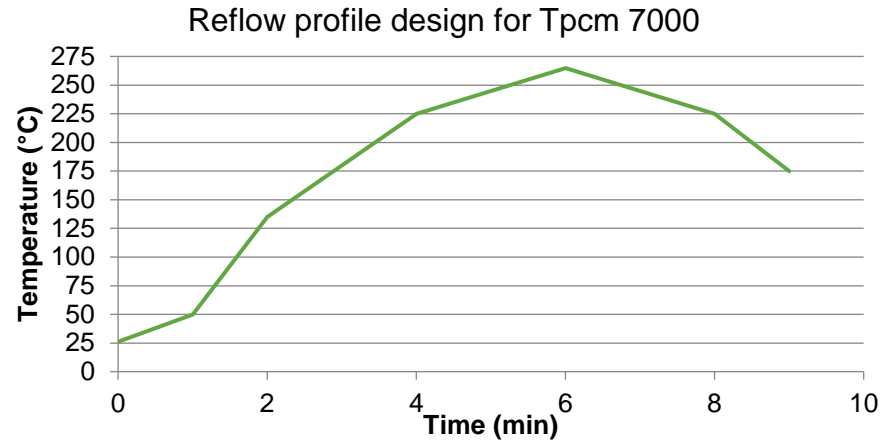
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Procedure

- Sample were place between 25mm aluminum disks under 15 psi.
- Initial thermal resistance was measured.
- Samples where then run through solder reflow and the thermal resistance was measure again.



Solder Reflow Oven



Test setup



Aluminum Disk measuring 1in² in area



Thermocouple location
Aluminum Disks Clamped with Sample



Close-Up of The Aluminum
Disks in the Thermal Tester



ASTM D5470 Thermal Resistance Tester

Results after 5 cycles

Tpcm 7000 change in thermal resistance after solder reflow

